



Recommended Pad Layout

- NOTES:
- 1.MATERIAL: BODY: HI-TEMP. PLASTIC, BLACK; UL 94V-0  
TERMINAL: COPPER ALLOY, T=0.20mm
  - 2.FINISH: TERMINAL: 50U"MINI UNDERPLATING OVERALL GOLD FLASH OVER PLATING ALL OVER
  - 3.ALL DIMENSIONS MARKED ∇ MUST BE CONTROLLED BY QC

REV.	DESCRIPTION	DESIGN
A0	Initial Release	

NO	DESCRIPTION	QTY	PLATING & COLOR
1	BODY	1	BLACK
2	RING SPRING	2	GOLD PLATING
3	SHUNT TERMINAL A	1	GOLD PLATING
4	SHUNT TERMINAL B	1	GOLD PLATING
5	TIP SPRING	1	GOLD PLATING
6	EARTH SPRING	1	GOLD PLATING



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PART NO.: HYP35004501  
TITLE: CUSTOMER DWG.  
φ3.5mm PHONE JACK

DIM	TOL	DIM	TOL
X	±0.30	X°	± 2°
XX	±0.25	X°	± 1°
XXX	±0.20	XX°	± 0.5°
	±0.15		

APP'D:	DWG NO.:
CHK'D:	UNITS: mm
DR:	SCALE: N/A
	SHEET: 1/1
	REV: A0